

Chemical content 74HCT00D-Q100



| Type number | Package | Package description | Total product weight |
|---------------|----------|---------------------|----------------------|
| 74HCT00D-Q100 | SOT108-1 | SO14 | 141.69570 mg |

| 12NC | Version | Pb-free soldering | | | Pb soldering | | | Number of processing cycles | Assembly site | RHF-indicator |
|--------------|---------|-------------------|-----|------|--------------|-----|------|-----------------------------|---|---------------|
| | | MSL | PPT | MPPT | MSL | PPT | MPPT | | | |
| 935298902118 | 5 | 1 | 260 | 30 s | 1 | 240 | 20 s | 3 | Nijmegen, Netherlands; Suzhou, China; Bangkok, Thailand | |

| Subpart | Material group | Substances | CAS number | Mass(mg) | Mass(%) of subpart | Mass(%) of total product |
|---------------------|------------------|--|-------------|----------|--------------------|--------------------------|
| Adhesive | Filler | Silver (Ag) | 7440-22-4 | 0.02336 | 77.86000 | 0.01648 |
| | Polymer | Acrylic resin | Proprietary | 0.00455 | 15.18000 | 0.00321 |
| | | Resin system | Proprietary | 0.00209 | 6.96000 | 0.00147 |
| | | subTotal | | 0.03000 | 100.00000 | 0.02116 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.26300 | 100.00000 | 0.18561 |
| | | subTotal | | 0.26300 | 100.00000 | 0.18561 |
| Lead Frame Material | Copper alloy | Copper (Cu) | 7440-50-8 | 47.74804 | 97.47000 | 33.69759 |
| | | Iron (Fe) | 7439-89-6 | 1.17570 | 2.40000 | 0.82973 |
| | | Phosphorous (P) | 7723-14-0 | 0.01470 | 0.03000 | 0.01037 |
| | | Zinc (Zn) | 7440-66-6 | 0.04899 | 0.10000 | 0.03457 |
| | | subTotal | | 48.98742 | 100.00000 | 34.57226 |
| Mould Compound | Additive | Non hazardous | Proprietary | 4.28097 | 4.70000 | 3.02124 |
| | Filler | Silica fused | 60676-86-0 | 71.95676 | 79.00000 | 50.78260 |
| | Flame retardant | Magnesium Hydroxide (Mg(OH)2) | 1309-42-8 | 5.46507 | 6.00000 | 3.85691 |
| | Pigment | Carbon black | 1333-86-4 | 0.18217 | 0.20000 | 0.12856 |
| | Polymer | 1.4-bis(methoxymethyl)benzene/phenol copolymer | 26834-02-6 | 3.64338 | 4.00000 | 2.57127 |
| | | Non hazardous | Proprietary | 3.73446 | 4.10000 | 2.63555 |
| | | Tetramethylbiphenyl diglycidyl ether | 85954-11-6 | 1.82169 | 2.00000 | 1.28564 |
| | | subTotal | | 91.08450 | 100.00000 | 64.28177 |
| Pre-Plating | Pure metal layer | Gold (Au) | 7440-57-5 | 0.03731 | 3.00000 | 0.02633 |
| | | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 1.14778 | 92.30000 | 0.81003 |
| | | Palladium (Pd) | 7440-05-3 | 0.03855 | 3.10000 | 0.02721 |
| | | Silver (Ag) | 7440-22-4 | 0.01990 | 1.60000 | 0.01404 |
| | | subTotal | | 1.24353 | 100.00000 | 0.87761 |
| Wire | Pure metal | Copper (Cu) | 7440-50-8 | 0.08724 | 100.00000 | 0.06157 |
| | | subTotal | | 0.08724 | 100.00000 | 0.06157 |

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.